

L Number	Hits	Search Text	DB	Time stamp
1	13095	(chip or die) and ((pad or land) with (solder or ball or balls))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:30
2	4231	(chip or die) and ((pad or land) with (balls or bumps))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 22:04
3	2844	((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:10
4	86	((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 20:59
5	263	((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:26
6	229	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:32
7	3	6291897.URPN.	USPAT	2004/03/07 21:12
8	29	("Re27934" "3202888" "4263606" "4390771" "4597519" "4804132" "5207585" "5214308" "5329423" "5373111" "5426266" "5428298" "5457344" "5508561" "5532613" "5545589" "5545920" "5550083" "5559054" "5559366" "5585282" "5592736" "5656858" "5726501" "5726502" "5736790" "5783865" "5783870" "5801449").PN.	USPAT	2004/03/07 21:12
9	9	("2934685" "3809625" "3871014" "4369458" "4600600" "4838347" "5001542" "5010038" "5207585").PN.	USPAT	2004/03/07 21:21
10	1	5955784.URPN.	USPAT	2004/03/07 21:22
11	166	((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:24
12	115	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:26
13	96	((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:26

14	55	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:26
15	3	6444563.URPN.	USPAT	2004/03/07 21:27
16	4	("3871015" "5266520" "6020561" "6066551").PN.	USPAT	2004/03/07 21:27
17	4231	(chip or die) and ((pad or land) with (balls or bumps))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:32
18	2844	((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:31
19	2362	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:31
20	1770	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:32
21	1699	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:58
22	1508	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:33
23	1486	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:12

24	946	(((((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.)) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:11
25	447	(((((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.)) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:57

26	66	(((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.) and 438/\$.ccls.) not ((((((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.) and 257/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 21:58
27	1	("5955784").PN.	USPAT	2004/03/07 22:03
28	128	((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (round or rounded or circle or semicircle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 22:05
30	749	((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (x or v or l or shape or round or rounded or circle or semicircle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 22:08
29	74	((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (round or rounded or circle or semicircle))) and (@ad<20010212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 22:05
31	189	((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (x or v or l))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 22:08
32	124	((chip or die) and ((pad or land) with (balls or bumps))) and ((pad or land) with (x or v or l))) and (@ad<20010212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 22:57
33	1	("5578527").PN.	USPAT	2004/03/07 22:57
34	3574	((chip or die) and ((pad or land) with (balls or bumps))) and (@ad<20020212)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:26

35	2060	((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20020212)) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:26
36	1114	((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20020212)) and 257/\$.ccls.) not ((((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.) not (((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)) not (((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.)) and 257/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:13
37	868	((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20020212)) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:26
38	868	((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20020212)) and 438/\$.ccls.) and (@ad<20020212))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:26
39	536	(((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20020212)) and 438/\$.ccls.) and (@ad<20020212)) not ((((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20020212)) and 257/\$.ccls.) not ((((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and (semiconductor or ic)) and (solder with (balls or bumps))) not (((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)) not (((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/778.ccls.) not (((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/777.ccls.)) not (((((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/779.ccls.) not (((chip or die) and (pad or land) with (balls or bumps))) and (@ad<20010212)) and 257/780.ccls.)) and 257/\$.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/07 23:27